# 4 Pin Optocoupler with Phototransistor Output

Description

The K817P Series consist of a phototransistor optically coupled to a gallium arsenide infrared-emitting diode in an 4-lead plastic dual inline package.

The elements are mounted on one leadframe using a coplanar technique, providing a fixed distance between input and output for highest safety requirements.
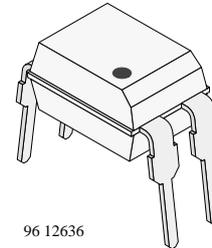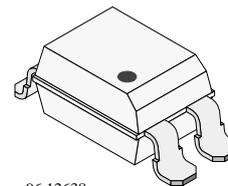
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Applications

Programmable logic controllers, modems, answering machines, general applications

Features

- Endstackable to 2.54 mm (0.1") spacing

- K817PW version suitable for **S**urface **M**ount **T**echnology (SMD)

- DC isolation test voltage $V_{IO} = 2.5$ kV

- Low coupling capacitance of typical 0.3 pF

- **C**urrent **T**ransfer **R**atio (CTR) selected into groups

- Low temperature coefficient of CTR

- Wide ambient temperature range

- **U**nderwriters **L**aboratory (UL) recognized-file No. E 76222 *

*   is applied

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Pin Connection

12590

Preliminary Information

K817P Series
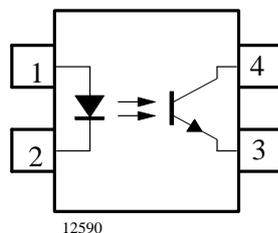
Order Schematic

Part Numbers	CTR-Ranking
K817P/K817PW [1]	50 to 600%
K817P1/K817P1W [2]	40 to 80%
K817P2/K817P2W [2]	63 to 125%
K817P3/K817P3W [2]	100 to 200%
K817P5/K817P5W [1]	50 to 150%
K817P6/K817P6W [1]	100 to 300%
K817P7/K817P7W [1]	80 to 160%
K817P8/K817P8W [1]	130 to 260%

Suffix: W   = Leadform Gullwing
[1] I_F = 5 mA / V_{CE} = 5 V
[2] I_F = 10 mA / V_{CE} = 10 V

Absolute Maximum Ratings

Input (Emitter)

Parameters	Test Conditions	Symbol	Value	Unit
Reverse voltage		V_R	6	V
Forward current		I_F	60	mA
Forward surge current	$t_p \leq 10$ μs	I_{FSM}	1.5	A
Power dissipation	$T_{amb} \leq 25°C$	P_v	100	mW
Junction temperature		T_j	125	°C

Output (Detector)

Parameters	Test Conditions	Symbol	Value	Unit
Collector emitter voltage		V_{CEO}	70	V
Emitter collector voltage		V_{ECO}	7	V
Collector current		I_C	50	mA
Peak collector current	$t_p/T = 0.5$, $t_p \leq 10$ ms	I_{CM}	100	mA
Power dissipation	$T_{amb} \leq 25°C$	P_v	150	mW
Junction temperature		T_j	125	°C

Coupler

Parameters	Test Conditions	Symbol	Value	Unit
DC Isolation test voltage		V_{IO}[1]	2.5	kV
Total power dissipation	$T_{amb} \leq 25°C$	P_{tot}	250	mW
Operating ambient temperature range		T_{amb}	–40 to +100	°C
Storage temperature range		T_{stg}	–55 to +125	°C
Soldering temperature	2 mm from case, $t \leq 10$ s	T_{sd}	260	°C

[1]   Related to standard climate 23/50 DIN 50014

Preliminary Information

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Electrical Characteristics

$T_{amb} = 25°C$

Input (Emitter)

Parameters	Test Conditions	Symbol	Min.	Typ.	Max.	Unit
Forward voltage	I_F = 50 mA	V_F		1.25	1.6	V
Reverse current	V_R = 6 V	I_R			10	μA

Output (Detector)

Parameters	Test Conditions	Symbol	Min.	Typ.	Max.	Unit
Collector emitter voltage	I_C = 100 μA	V_{CEO}	70			V
Emitter collector voltage	I_E = 100 μA	V_{ECO}	7			V
Collector dark current	V_{CE} = 20 V, I_F = 0, E = 0	I_{CEO}			100	nA

Coupler

Parameters	Test Conditions	Symbol	Min.	Typ.	Max.	Unit
DC isolation test voltage	t = 2 s	V_{IO}[1]	2.5			kV
Isolation resistance	V_{IO} = 1000 V, 40% rel. humidity	R_{IO}[1]	10^{10}	10^{12}		Ω
Collector emitter saturation voltage	I_F = 10 mA, I_C = 1 mA	V_{CEsat}			0.3	V
Cut-off frequency	I_F = 10 mA, V_{CE} = 5 V, R_L = 100 Ω	f_c		100		kHz
Coupling capacitance	f = 1 MHz	C_k		0.3		pF

[1] Related to standard climate 23/50 DIN 50014

Current Transfer Ratio (CTR)

Parameters	Test Conditions	Type	Symbol	Min.	Typ.	Max.	Unit
I_C/I_F	V_{CE} = 10 V, I_F = 10 mA	K817P1(W)	CTR	0.4		0.8	
I_C/I_F	V_{CE} = 10 V, I_F = 10 mA	K817P2(W)	CTR	0.63		1.25	
I_C/I_F	V_{CE} = 10 V, I_F = 10 mA	K817P3(W)	CTR	1.0		2.0	
I_C/I_F	V_{CE} = 5 V, I_F = 5 mA	K817P(W)	CTR	0.5		6.0	
I_C/I_F	V_{CE} = 5 V, I_F = 5 mA	K817P5(W)	CTR	0.5		1.5	
I_C/I_F	V_{CE} = 5 V, I_F = 5 mA	K817P6(W)	CTR	1.0		3.0	
I_C/I_F	V_{CE} = 5 V, I_F = 5 mA	K817P7(W)	CTR	0.8		1.6	
I_C/I_F	V_{CE} = 5 V, I_F = 5 mA	K817P8(W)	CTR	1.3		2.6	

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Switching Characteristics (Typical Values)

$V_S = 5$ V

Type	$R_L = 100\ \Omega$ (see figure 1)							$R_L = 1\ k\Omega$ (see figure 2)		
	$t_d[\mu s]$	$t_r[\mu s]$	$t_{on}[\mu s]$	$t_s[\mu s]$	$t_f[\mu s]$	$t_{off}[\mu s]$	$I_C[mA]$	$t_{on}[\mu s]$	$t_{off}[\mu s]$	$I_F[mA]$
K817P(W) Series	3.0	3.0	6.0	0.3	4.7	5.0	2	9	18	10

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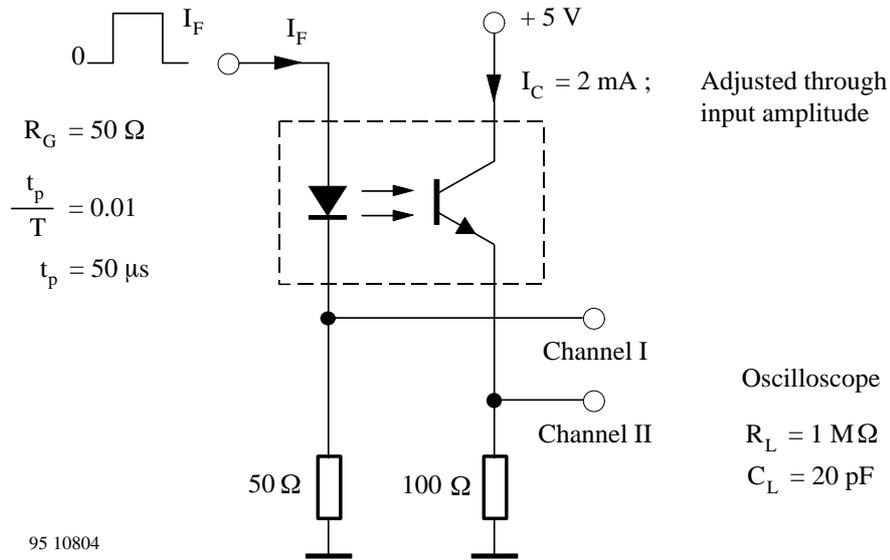
Figure 1. Test circuit, non-saturated operation

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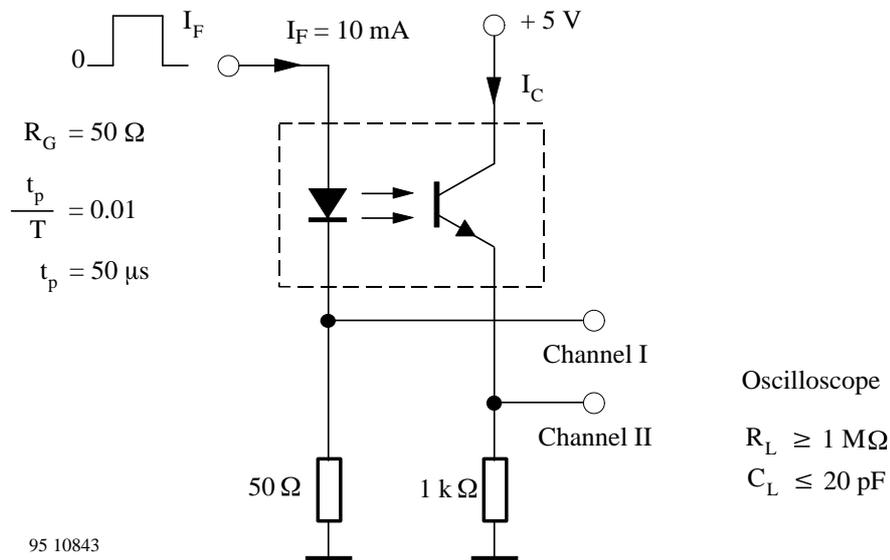
Figure 2. Test circuit, saturated operation

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Preliminary Information

Typical Characteristics (T_{amb} = 25°C, unless otherwise specified)
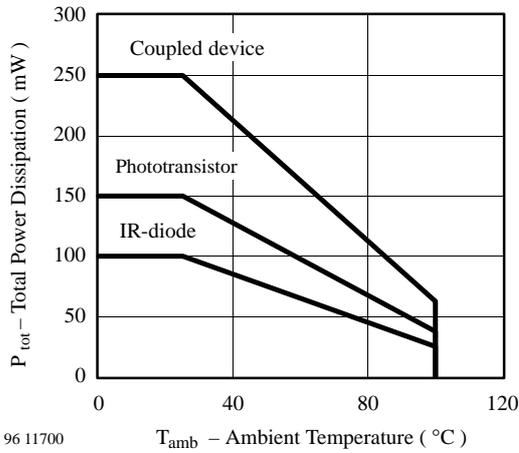
Figure 3. Total Power Dissipation vs. Ambient Temperature
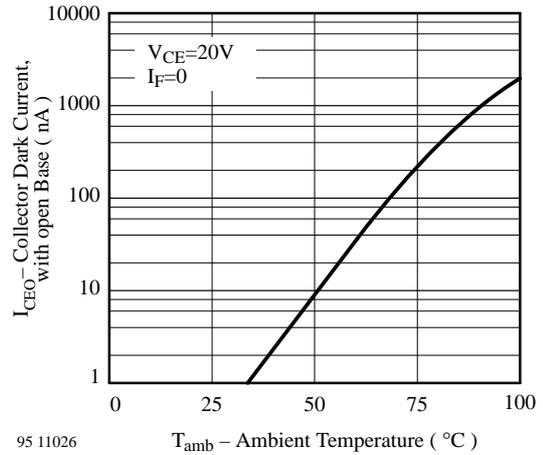
Figure 6. Collector Dark Current vs. Ambient Temperature
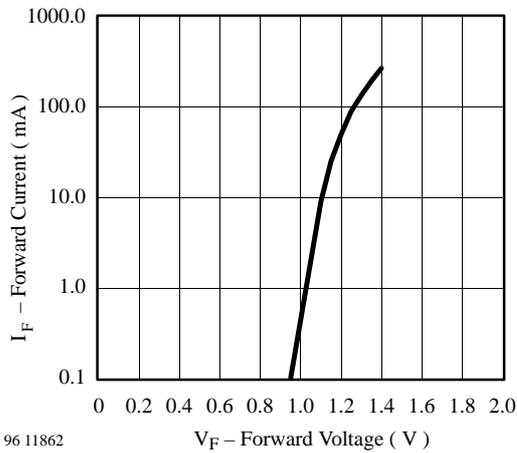
Figure 4. Forward Current vs. Forward Voltage
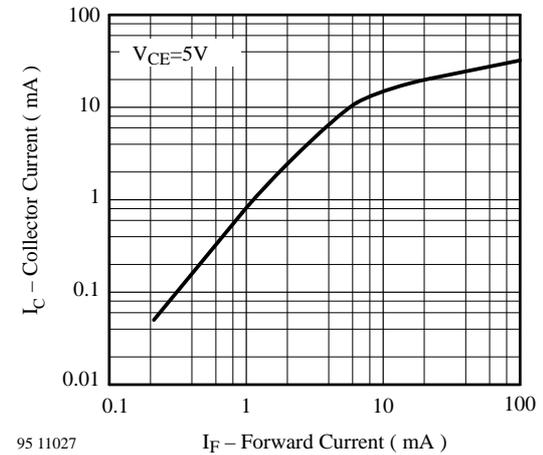
Figure 7. Collector Current vs. Forward Current
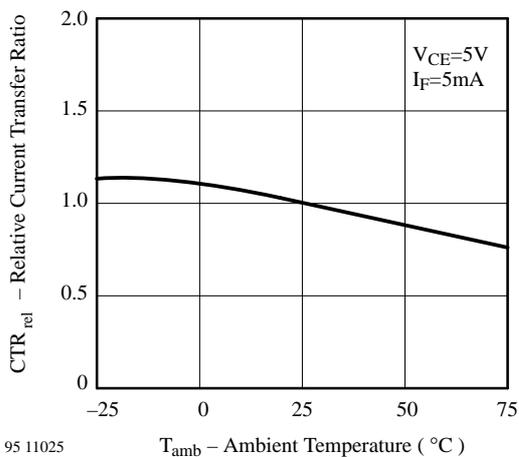
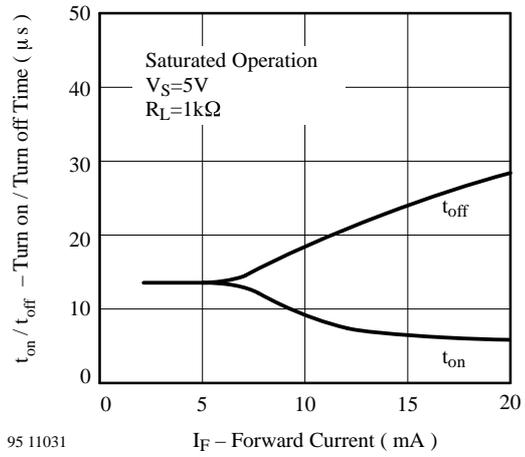Figure 5. Rel. Current Transfer Ratio vs. Ambient Temperature
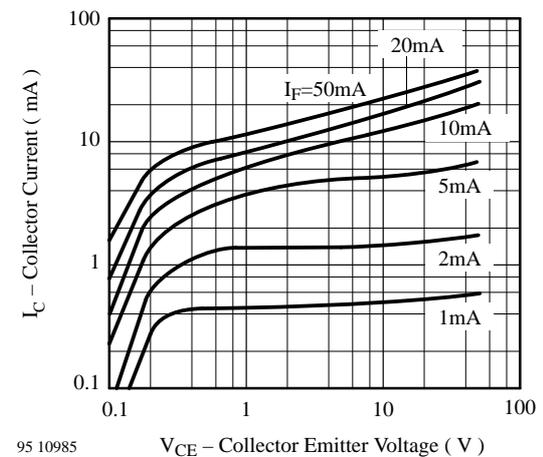
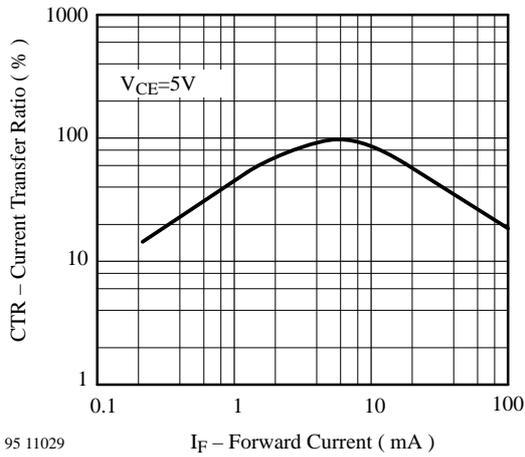Figure 8. Collector Current vs. Collector Emitter Voltage

Preliminary Information

Typical Characteristics ($T_{amb} = 25°C$, unless otherwise specified)
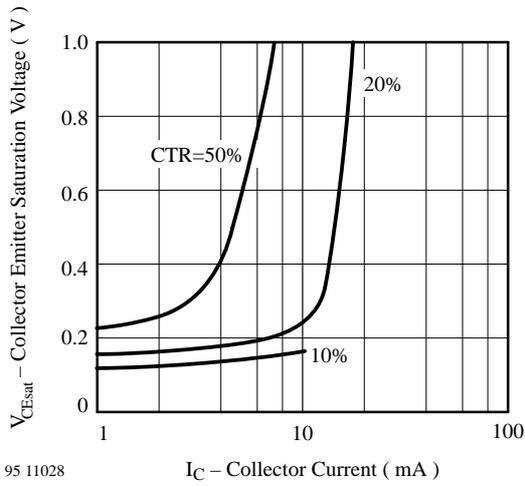
Figure 9. Collector Emitter Sat. Voltage vs. Collector Current
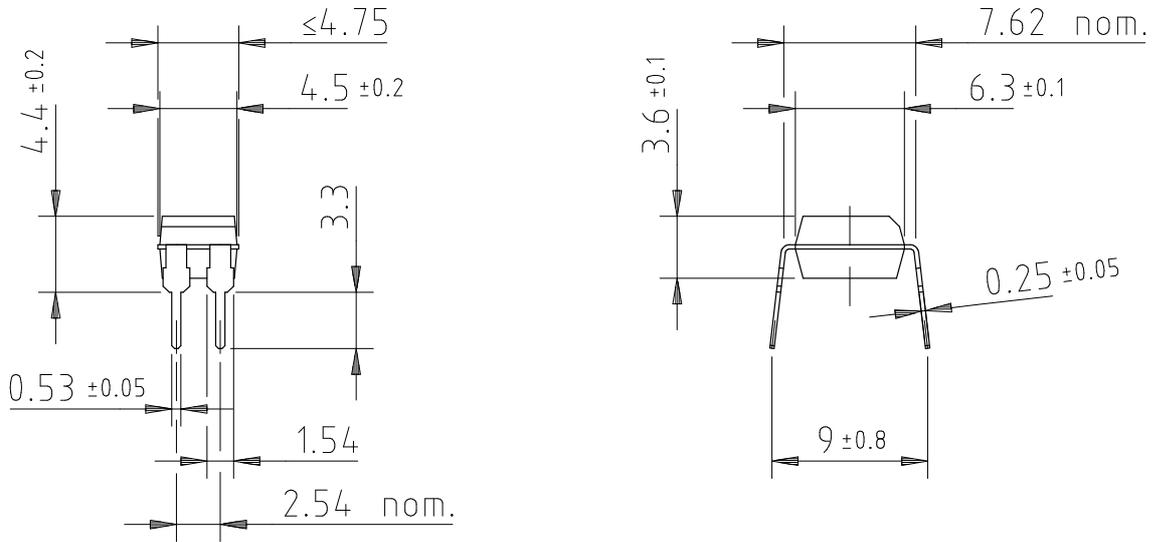

Figure 11. Turn on / off Time vs. Forward Current

Figure 10. Current Transfer Ratio vs. Forward Current
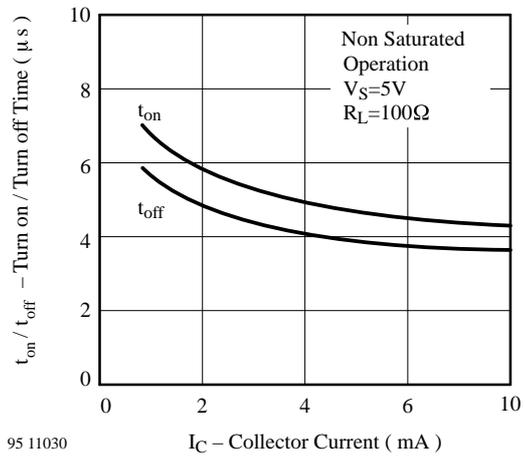
Figure 12. Turn on / off Time vs. Collector Current

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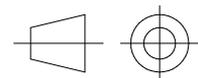
Preliminary Information

Dimensions in mm

E.g.:
special Features: endstackable
to 2.54mm (.100") spacing
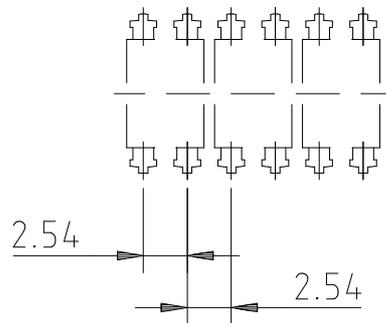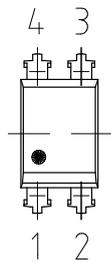
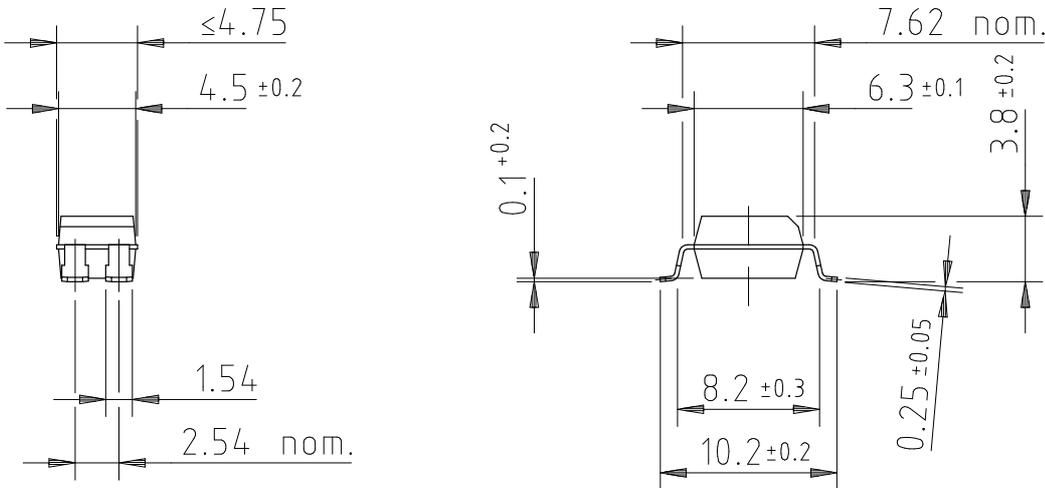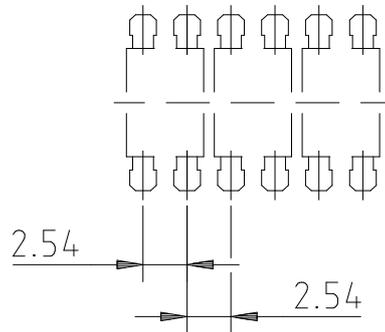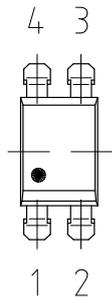96 12231

technical drawings
according to DIN
specifications

Preliminary Information

Dimensions in mm

≤4.75

4.5 ±0.2

1.54

2.54 nom.

7.62 nom.

6.3 ±0.1

3.8 ±0.2

0.1 +0.2

8.2 ±0.3

10.2 ±0.2

0.25 ±0.05

4 3

1 2

E.g.:

special Features: endstackable
to 2.54mm (.100″) spacing

2.54

2.54
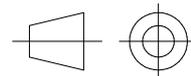
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technical drawings
according to DIN
specifications

Preliminary Information

Ozone Depleting Substances Policy Statement

It is the policy of **TEMIC TELEFUNKEN microelectronic GmbH** to

1. Meet all present and future national and international statutory requirements.

2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

TEMIC TELEFUNKEN microelectronic GmbH semiconductor division has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively

2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA

3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

TEMIC can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

Preliminary Information